Electrical Characteristics at Tc = 25°C, VD1, VD2, VD3, VD4 = 15 V

		Conditions		Test		Ratings		Linit
Parameter	Symbol			circuit	Min.	Тур.	Max.	Unit
Power output section	I	I		· I		I	I	l
Collector to emitter cut-off current	ICE	V _{CE} = 600 V		Fig. 1	-	-	100	μΑ
Bootstrap diode reverse current	IR(BD)	VR(BD) = 600 V		Fig.1	-	-	100	μA
		In - 50 A	Upper side		-	1.7	2.6	
Collector to emitter saturation	., , ,	Ic = 50 A	Lower side		-	2.3	3.2	
voltage	V _{CE} (sat)	Ic = 25 A.	Upper side	Fig.2	-	1.35	-	V
-		Tj = 100°C	Lower side		-	1.75	-	
		IF = 50 A	Upper side		-	1.8	2.7	
D: 1 6 1 1		II - 30 A	Lower side	F: 0	-	2.4	3.3	1 ,,
Diode forward voltage	VF	IF = 25 A,	Upper side	Fig.3	_	1.45	_	V
		Tj = 100°C	Lower side		_	1.85	_	1
	Oi o/T)	IGBT	LOWEI SIGE		_	1.5		°C/W
Junction to case thermal resistance	θj-c(T)			-	-		-	
Cantral (Dra driver)	θj-c(D)	FWD		-	-	1.8	-	°C/W
Control (Pre-driver) section	I	T						
Pre-drive power supply consumption	ID	VD1, 2, 3 = 15 V		Fig.4	-	0.05	0.4	mA
current		VD4 = 15 V			-	1.0	4.0	
High level input voltage	Vin H	HIN1, HIN2, HIN3,		-	2.5	-	-	V
Low level input voltage	Vin L	LIN1, LIN2, LIN3 to V _{SS}		-	-	-	0.8	V
Logic 1 input leakage current	I _{IN+}	VIN = +3.3 V				100	195	μΑ
Logic 0 input leakage current	I _{IN-}	VIN = 0 V					1	μA
Protection section	ı	T		1		ı	l	1
Over-current protection electric current	ISD	PW = 100 μ s, RSD = 0 Ω		Fig.5	57	-	76	Α
V _{DD} and V _{Bx} supply undervoltage	V_{ddUV+}				10.6	11.1	11.6	V
positive going input threshold	V _{BxUV+}							
V _{DD} and V _{Bx} supply undervoltage	V _{ddUV-}				10.4	10.9	11.4	V
negative going input threshold VDD and VBx supply undervoltage	$V_{\text{BxUV-}}$							
I _{lockout} hysteresis	V _{ddUVH} V _{BxUVH}					0.2		V
FAULT terminal input electric current	IOSD	VFAULT = 0.1 V		_	1	1.5	_	mA
FAULT clearance delay time	FLTCLR	From time fault co	ondition clear	_	18	-	80	ms
Thermistor for substrate temperature		Resistance between						
monitor	Rt	and V _{SS} (20) term		-	90	-	110	kΩ
Switching character								
0 11 11	tON				-	0.7	1.5	μs
Switching time	tOFF	lo = 50 A, Inductiv	ve load		-	1.1	2.1	μs
Turn-on switching loss	Eon	Io = 50 A \/	200.1/		-	1100	-	μJ
Turn-off switching loss	Eoff	lo = 50 A, V _{CC} = 300 V,		Fig.6	-	1220	-	μJ
Total switching loss	Etot	VD = 15 V, L = 280 μH			-	2320	-	μJ
Turn-on switching loss	Eon	Io = 25 A, V _{CC} = 300 V,			-	620	-	μJ
Turn-off switching loss	Eoff	VD = 15 V, L = 280 μH,			-	790	-	μJ
Total switching loss	Etot	Tc = 100°C	200 \/		-	1410	-	μJ
Diode reverse recovery energy	Erec	Io = 25 A, V _{CC} = VD = 15 V, L = 28			-	27	-	μJ
Diode reverse recovery time	Trr	Tc = 100°C	•		-	80	-	ns
Reverse bias safe operating area	RBSOA	Io = 76 A, V _{CE} =			I	Full square	e	
Short circuit safe operating area	SCSOA	V _{CE} = 400 V, Tc :	= 100°C		4			μs
Electric current output signal level	ISO	Io = 50 A		-	0.427	0.45	0.474	V

Reference voltage is N terminal = V_{SS} terminal voltage unless otherwise specified.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Notes

1. When the internal protection circuit operates, a Fault signal is turned ON (When the Fault terminal is low level, Fault signal is ON state: output form is open DRAIN) but the Fault signal does not latch. After protection operation ends, it returns automatically within about 18 ms to 80 ms and resumes operation beginning condition. So, after Fault signal detection, set all input signals to OFF (Low) at once. However, the operation of pre-drive power supply low voltage protection (UVLO: with hysteresis about 0.2 V) is as follows.

Upper side:

The gate is turned off and will return to regular operation when recovering to the normal voltage, but the latch will continue till the input signal will turn 'low'.

Lower side:

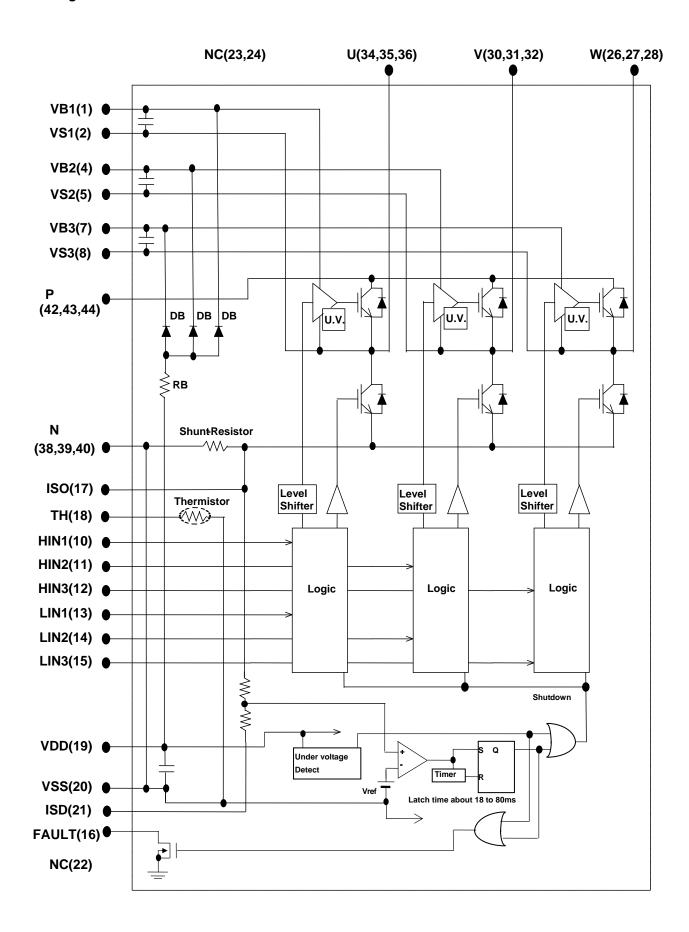
The gate is turned off and will automatically reset when recovering to normal voltage. It does not depend on input signal voltage.

- 2. When assembling the IPM on the heat sink with M4 type screw, tightening torque range is 0.79 Nm to 1.17 Nm.
- 3. The pre-drive low voltage protection is the feature to protect devices when the pre-driver supply voltage falls due to an operating malfunction.

Pin Assignment

Pin No.	Name	Description	Pin No.	Name	Description
1	VB1	High side floating supply voltage 1	44	Р	Positive bus input voltage
2	VS1	High side floating supply offset voltage	43	Р	Positive bus input voltage
3	-	Without pin	42	Р	Positive bus input voltage
4	VB2	High side floating supply voltage 2	41	-	Without pin
5	VS2	High side floating supply offset voltage	40	N	Negative bus input voltage
6	-	Without pin	39	N	Negative bus input voltage
7	VB3	High side floating supply voltage 3	38	N	Negative bus input voltage
8	VS3	High side floating supply offset voltage	37	-	Without pin
9	-	Without pin	36	U	U-phase output
10	HIN1	Logic input high side driver-Phase1	35	U	U-phase output
11	HIN2	Logic input high side driver-Phase2	34	U	U-phase output
12	HIN3	Logic input high side driver-Phase3	33	-	Without pin
13	LIN1	Logic input low side driver-Phase1	32	V	V-phase output
14	LIN2	Logic input low side driver-Phase2	31	V	V-phase output
15	LIN3	Logic input low side driver-Phase3	30	V	V-phase output
16	FAULT	Fault out (open drain)	29	-	Without pin
17	ISO	Current monitor pin	28	W	W-phase output
18	TH	Thermistor out	27	W	W-phase output
19	VDD	+15 V main supply	26	W	W-phase output
20	VSS	Negative main supply	25	-	Without pin
21	ISD	Over-current protection level setting pin	24	NC	-
22	NC	-	23	NC	-

Block Diagram



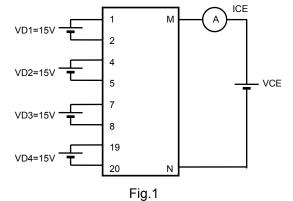
Test Circuit

(The tested phase : U+ shows the upper side of the U phase and U- shows the lower side of the U phase)

■ ICE / IR(BD)

ı		U+	V+	W+	U-	V-	W-
	M	42	42	42	34	30	26
	N	34	30	26	38	38	38

	U(BD)	V(BD)	W(BD)
M	1	4	7
N	20	20	20



■ V_{CE}(sat) (Test by pulse)

	U+	V+	W+	U-	V-	W-
M	42	42	42	34	30	26
N	34	30	26	17	19	21
m	10	11	12	13	14	15

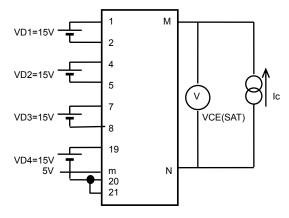
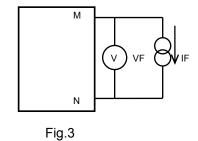


Fig.2

■ VF (Test by pulse)

	U+	V+	W+	U-	V-	W-
M	42	42	42	34	30	26
N	34	30	26	38	38	38



■ ID

	VD1	VD2	VD3	VD4
M	1	4	7	19
N	2	5	8	20

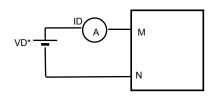
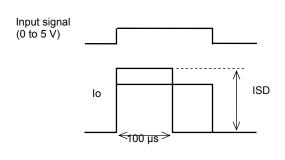


Fig.4

■ ISD



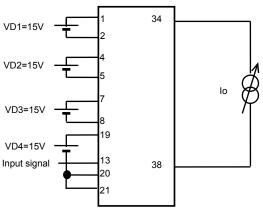
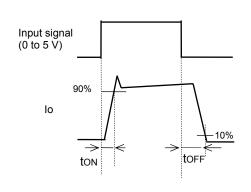
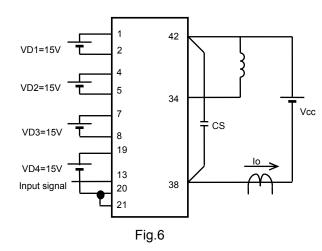


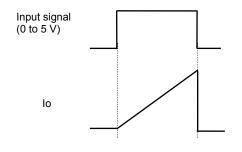
Fig.5

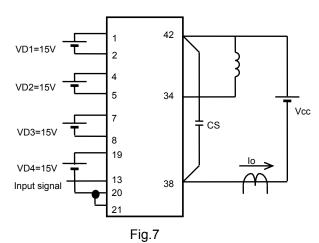
■ Switching time (The circuit is a representative example of the lower side U phase)





■ RB-SOA (The circuit is a representative example of the lower side U phase)





Logic Timing Chart

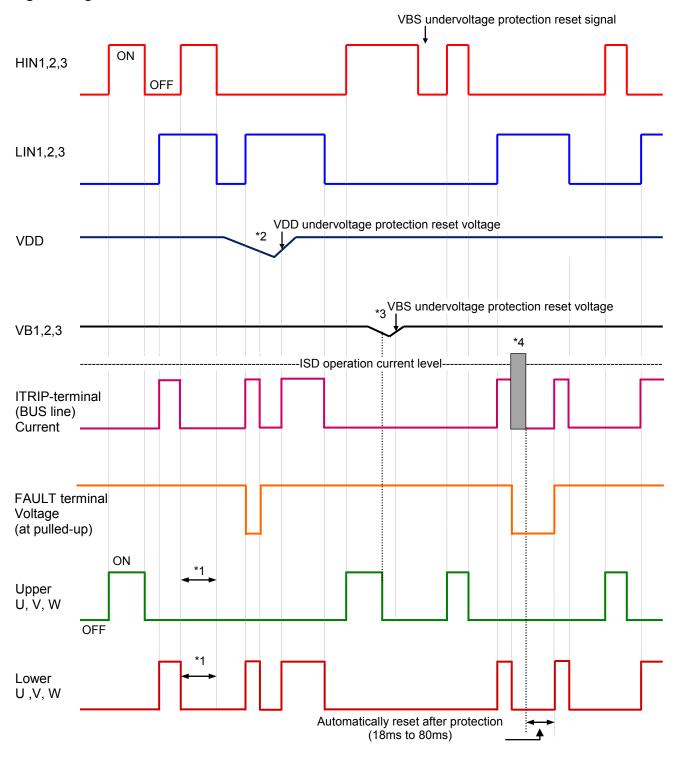
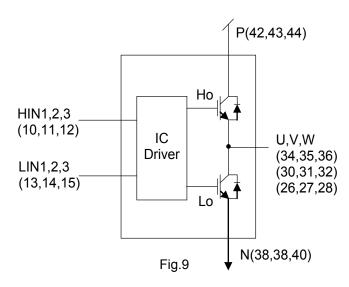


Fig. 8

Notes

- *1: Diagram shows the prevention of shoot-through via control logic. More dead time to account for switching delay needs to be added externally.
- *2: When V_{DD} decreases all gate output signals will go low and cut off all of 6 IGBT outputs. part. When V_{DD} rises the operation will resume immediately.
- *3: When the upper side gate voltage at VB1, VB2 and VB3 drops only, the corresponding upper side output is turned off. The outputs return to normal operation immediately after the upper side gat voltage rises.
- *4: In case of over current detection, all IGBT's are turned off and the FAULT output is asserted. Normal operation resumes in 18 to 80 ms after the over current condition is removed.

Logic level table



FAULT*	HIN1,2,3	LIN1,2,3	U,V,W
1	1	0	Vbus
1	0	1	0
1	0	0	Off
1	1	1	Off
0	X	X	Off

^{*} With pulled-up registor

Application Circuit Example

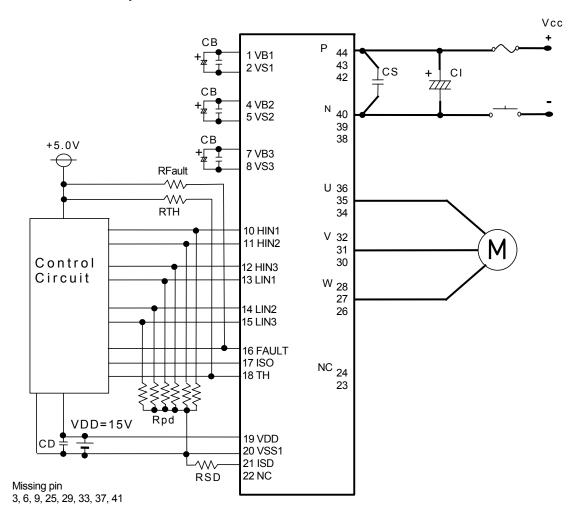


Fig.10

Recommended Operating Conditions at Tc = 25°C

Davamatan	Come had	Conditions		Ratings		
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Supply voltage	VCC	P to N	0	280	450	V
Pre-driver supply voltage	VD1, 2, 3	VB1 to VS1, VB2 to VS2, VB3 to VS3	12.5	15	17.5	V
Pre-univer supply voltage	VD4	V _{DD} to V _{SS} *1	13.5	15	16.5]
Input ON voltage	VIN(ON)	HIN1, HIN2, HIN3,	3.0	-	V_{DD}	V
Input OFF voltage	VIN(OFF)	LIN1, LIN2, LIN3	0	=	0.8	ľ
PWM frequency	fPWM		1	-	20	kHz
Dead time	DT	Turn-off to turn-on (external)	2	-	-	μs
Allowable input pulse width	PWIN	ON pulse width/OFF pulse width	1	-	-	μs
Tightening torque	MT	'M4' type screw	0.79	-	1.17	Nm

^{*1} Pre-driver power supply (VD4 = 15 ±1.5 V) must have the capacity of Io = 20 mA (DC), 0.5 A (Peak).

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Usage Precautions

- 1. This IPM includes bootstrap diode and resistors. Therefore, by adding a capacitor "CB", a high side drive voltage is generated; each phase requires an individual bootstrap capacitor. The recommended value of CB is in the range of 1 to 47 μF, however this value needs to be verified prior to production. If selecting the capacitance more than 47 μF (±20%), connect a resistor (about 20 Ω) in series between each 3-phase upper side power supply terminals (VB1, 2, 3) and each bootstrap capacitor.
 - When not using the bootstrap circuit, each upper side pre-drive power supply requires an external independent power supply.
- 2. It is essential that wirning length between terminals in the snubber circuit be kept as short as possible to reduce the effect of surge voltages. Recommended value of "CS" is in the range of 0.1 to 10 μF.
- 3. "ISO" (pin 17) is terminal for current monitor. When the pull-down resistor is used, please select it more than 5.6 k Ω .
- 4. "FAULT" (pin 16) is open DRAIN output terminal. (Active Low). Pull up resistor is recommended more than 5.6 kΩ.
- 5. Inside the IPM, a thermistor used as the temperature monitor for internal subatrate is connected between VSS terminal and TH terminal, therefore, an external pull up resistor connected between the TH terminal and an external power supply should be used. The temperature monitor example application is as follows, please refer the Fig.11, and Fig.12 below.
- 6. The pull down resistor of 33 k Ω is provided internally at the signal input terminals. An external resistor of 2.2 k Ω to 3.3 k Ω should be added to reduce the influence of external wiring noise.
- 7. The over-current protection feature is not intended to protect in exceptional fault condition. An external fuse is recommended for safety.
- 8. When "N" and "VSS" terminal are short-circuited on the outside, level that over-current protection (ISD) might be changed from designed value as IPM. Please check it in your set ("N" terminal and "VSS" terminal are connected in IPM).
- The over-current protection function operates normally when an external resistor RSD is connected between ISD and VSS terminals. Be sure to connect this resistor. The level of the overcurrent protection can be changed according to the RSD value.
- 10. When input pulse width is less than 1.0 μ s, an output may not react to the pulse. (Both ON signal and OFF signal)

This data shows the example of the application circuit, does not guarantee a design as the mass production set.

The characteristic of thermistor

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Resistance	R ₂₅	Tc = 25°C	97	100	103	kΩ
Resistance	R ₁₀₀	Tc = 100°C	4.93	5.38	5.88	kΩ
B-Constant (25 to 50°C)	В		4165	4250	4335	K
Temperature Range			-40		+125	°C

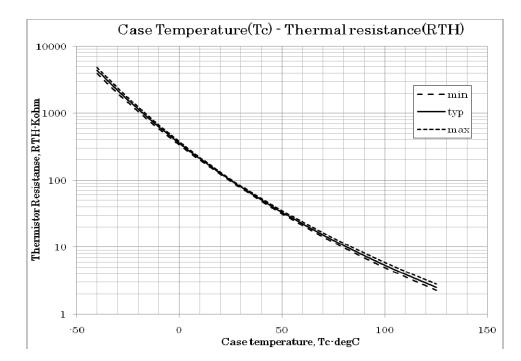


Fig.11 Variation of thermistor resistance with temperature

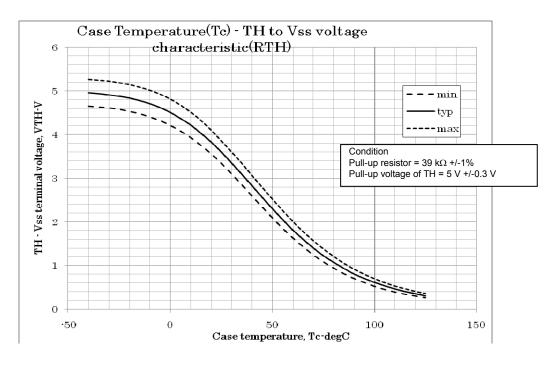


Fig.12 Variation of temperature sense voltage with thermistor temperature

Maximum Phase current

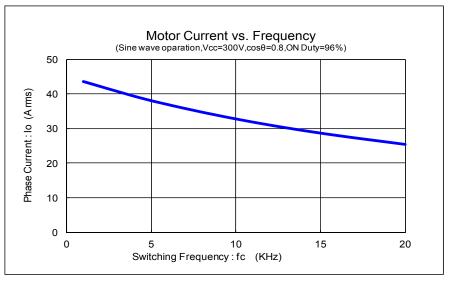


Fig.13 Maximum sinusoidal phase current as function of switching frequency at Tc = 100°C, V_{CC} = 300 V

Switching waveform

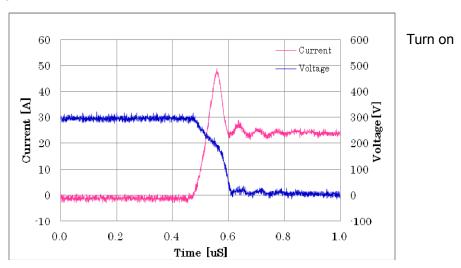


Fig. 14 IGBT Turn-on. Typical turn-on waveform at Tc = 100° C, V_{CC} = 300 V, Ic = 25 A

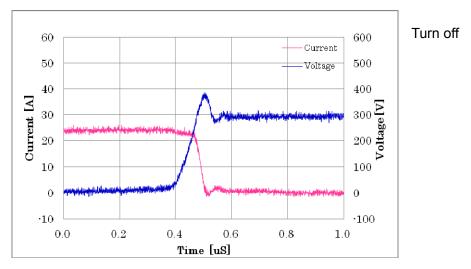


Fig. 15 IGBT Turn-off. Typical turn-off waveform Tc = 100° C, V_{CC} = 300 V, Ic = 25 A

CB capacitor value calculation for bootstrap circuit

Calculate condition

Item	Symbol	Value	Unit
Upper side power supply	VBS	15	V
Total gate charge of output power IGBT at 15 V	Qg	0.47	μC
Upper side power supply low voltage protection	UVLO	12	V
Upper side power dissipation	IDmax	400	μΑ
ON time required for CB voltage to fall from 15 V to UVLO	Ton-max	_	S

Capacitance calculation formula

CB must not be discharged below to the upper limit of the UVLO - the maximum allowable on-time (Ton-max) of the upper side is calculated as follows :

The relationship between Ton-max and CB becomes as follows. CB is recommended to be approximately 3 times the value calculated above. The recommended value of CB is in the range of 1 to 47 μ F, however, the value needs to be verified prior to production.

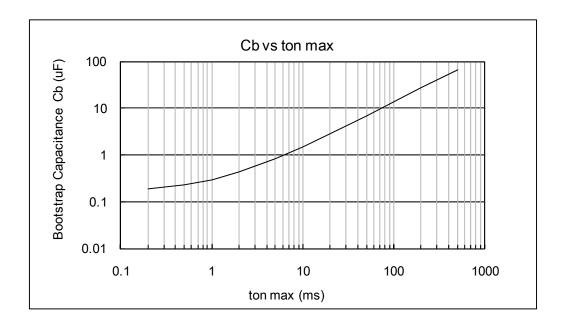


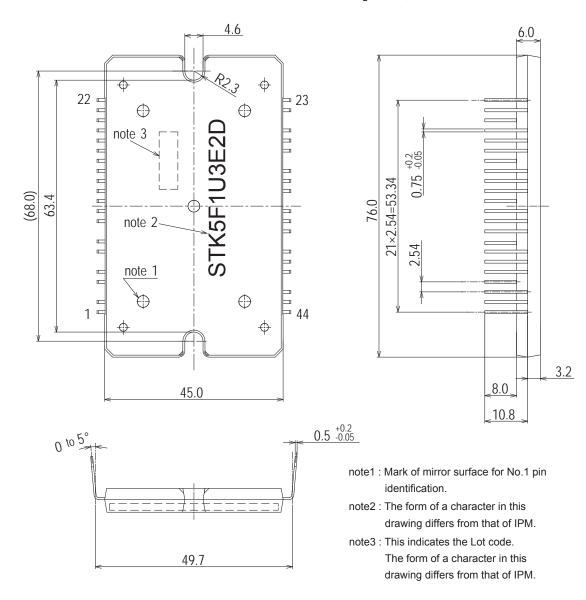
Fig.16 Ton-max vs CB characteristic

PACKAGE DIMENSIONS

unit: mm

TENTATIVE

Missing Pin: 3, 6, 9, 25, 29, 33, 37, 41



ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
STK5F1U3E2D-E	TBD (Pb-Free)	6 / Tube

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